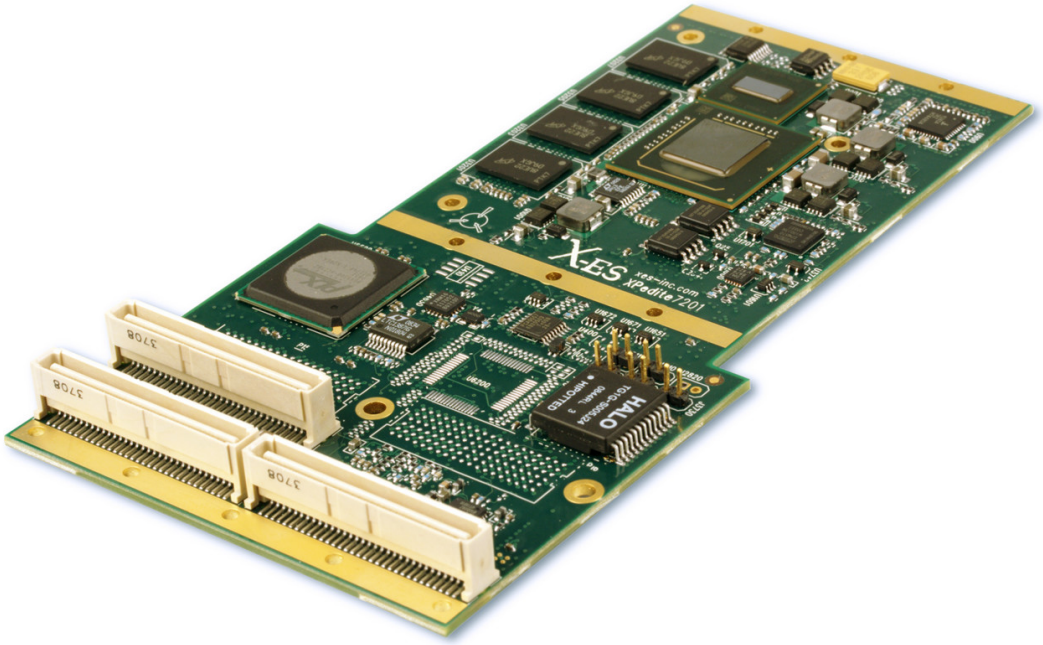
XPedite7201

End Of Life

Intel® Atom™ Processor-Based Conduction- or Air-Cooled XMC/PMC Module

- Intel® Atom™ Z530 processor at up to 1.6 GHz
- Conduction- or air-cooled XMC/PMC module
- 1 GB of DDR2-533 SDRAM
- Up to 4 GB of NAND flash
- x1 PCI Express XMC interface
- 32-bit, 66 MHz PCI PMC interface
- Gigabit Ethernet port with integrated magnetics
- Four USB 2.0 high-speed ports
- Two RS-232/422/485 serial ports
- Dual DVI-D video
- Audio line-in/out
- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers



XPedite7201

The XPedite7201 is a high-performance, low-power, conduction- or air-cooled, XMC/PMC module based on the Intel® Atom™ Z530 processor. With a x1 PCI Express or 32-bit, 66 MHz PCI interconnect and a Gigabit Ethernet port, the XPedite7201 is ideal for high-bandwidth data-processing applications.

The XPedite7201 accommodates 1 GB of DDR2-533 SDRAM to support memory-intensive applications and hosts numerous I/O ports including Gigabit Ethernet, USB 2.0, RS-232/422/485, and dual DVI-D video.

Linux 2.6, Wind River VxWorks, QNX Neutrino, and Green Hills INTEGRITY Board Support Packages (BSPs), as well as Microsoft Windows drivers, are available for the XPedite7201. The XPedite7201 also features UEFI system firmware.

X-ES Extreme Engineering Solutions

...Always Fast

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Processor

- Intel® Atom™ Z530 processor at up to 1.6 GHz

Memory

- Up to 1 GB of DDR2-533 SDRAM in one channel
- Up to 4 GB of NAND flash

XMC/PMC Interface

- 32-bit, 66 MHz PCI bus (PMC interface)
- x1 PCIe port (XMC interface)

P14 I/O

- One DVI-D video interface port
- Two USB 2.0 ports
- Two RS-232/422/485 ports
- One 10/100/1000BASE-T Ethernet port
- Audio I/O

P16 I/O

- Dual DVI-D video interface port
- One 10/100/1000BASE-T Ethernet port
- Two RS-232/422/485 ports
- Two USB 2.0 ports
- Audio I/O

Software

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers

Physical Characteristics

- XMC/PMC conduction- or air-cooled form factor
- Dimensions: 149 mm x 74 mm, 10 mm stacking height

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C ambient
Vibration	0.002 g²/Hz, 5 to 2000 Hz	0.04 g²/Hz (maximum), 5 to 2000 Hz	0.1 g²/Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing